TI 8

COMPLIANT

HALOGEN

GREEN

(5-2008)



Solid Tantalum Chip Capacitors, MICROTAN<sup>®</sup>, High CV Leadframeless Molded Low Profile



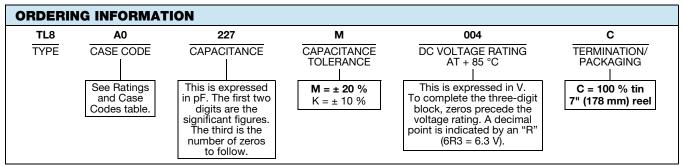
### **PERFORMANCE CHARACTERISTICS**

**Operating Temperature:** - 55 °C to + 125 °C (above 85 °C, voltage derating is required)

### FEATURES

- Ultra-low profile: 0.8 mm to 1.0 mm in a variety of case sizes
- Highest capacitance-voltage product in industry
  RoHS
- Lead (Pb)-free L-shaped terminations for superior board mounting
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Capacitance Tolerance:  $\pm 10 \% \pm 20 \%$ Voltage Range:  $4 V_{DC}$  to  $35 V_{DC}$ Capacitance Range:  $3.3 \mu$ F to  $220 \mu$ F



Note

Preferred tolerance and reel sizes are in bold.

We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size. Voltage substitutions will be marked with the higher voltage rating.

DIMENSIONS	in inches [millin	neters]				
C P1	P2 P1	Anode Ter	mination An	ode Polarity Bar	Catho	de Termination
CASE CODE	H (MAX.)	L	w	P1	P2 (REF.)	С
WO	0.039 [1.0]	0.079 ± 0.008	0.050 ± 0.008	0.020 ± 0.004	0.040	0.035 ± 0.004
W9	0.035 [0.9]	[2.00 ± 0.20]	[1.25 ± 0.20]	[0.50 ± 0.10]	[1.00]	[0.90 ± 0.10]
A0	0.039 [1.0]	0.126 ± 0.008 [3.20 ± 0.20]	0.063 ± 0.008 [1.60 ± 0.20]	0.031 ± 0.004 [0.80 ± 0.10]	0.063 [1.60]	0.047 ± 0.004 [1.20 ± 0.10]
B0	0.039 [1.0]	0.138 ± 0.008 [3.50 ± 0.20]	0.110 ± 0.008 [2.80 ± 0.20]	0.031 ± 0.004 [0.80 ± 0.20]	0.078 [1.95]	0.095 ± 0.004 [2.40 ± 0.10]

Document Number: 40156

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>

TL8



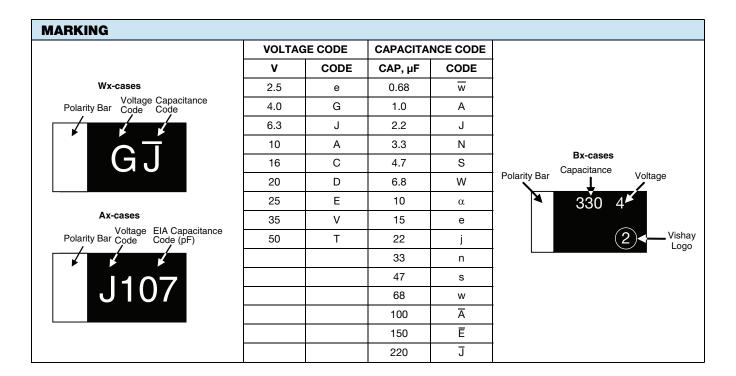
www.vishay.com

# Vishay Sprague

RATINGS	AND CASE C	ODES					
μF	4 V	6.3 V	10 V	16 V	20 V	25 V	35 V
1.5							
2.2							
3.3							A0 <sup>(1)</sup>
4.7						W0 <sup>(1)</sup>	
6.8							
10				W0 <sup>(1)</sup>	A0 <sup>(1)</sup>		
15							
22			W9				
33			W0 <sup>(1)</sup>		B0		
47		W0 <sup>(1)</sup>	W9 <sup>(1)</sup> /A0 <sup>(1)</sup>				
68							
100		A0	A0/B0 <sup>(1)</sup>				
150							
220	A0						
330							
470							

Note

<sup>(1)</sup> In development.



2

For technical questions, contact: <u>tantalum@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u> www.vishay.com

Vishay Sprague

STANDARD R	ATINGS					
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT + 25 °C (μΑ)	MAX. DF AT + 25 °C 120 Hz (%)	MAX. ESR AT + 25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I <sub>RMS</sub> (A)
		4 V <sub>DC</sub> AT + 40 °C; 2	2.5 V <sub>DC</sub> + 85 °C; 1.6 V <sub>DC</sub>	AT + 125 °C		
220	A0	TL8A0227M004C	88	80	7.0	0.089
		6.3 V <sub>DC</sub> AT + 40 °C;	4.0 V <sub>DC</sub> + 85 °C; 2.5 V <sub>D</sub>	<sub>C</sub> AT + 125 °C		
47	W0 <sup>(1)</sup>	TL8W0476M6R3C	3.0	25	3.0	0.108
100	A0	TL8A0107M6R3C	6.3	30	1.1	0.220
		10 V <sub>DC</sub> AT + 40 °C;	6.3 V <sub>DC</sub> + 85 °C; 4.0 V <sub>DC</sub>	<sub>2</sub> AT + 125 °C		
22	W9	TL8W9226M010C	22	40	10.0	0.084
33	W0 <sup>(1)</sup>	TL8W0336M010C	3.3	30	6.0	0.076
47	W9 <sup>(1)</sup>	TL8W9476M010C	9.4	35	5.0	0.084
47	A0 <sup>(1)</sup>	TL8A0476M010C	15	30	5.0	0.105
100	A0	TL8A0107M010C	100	50	7.0	0.089
100	B0 <sup>(1)</sup>	TL8B0107M010C	10	18	TBD	TBD
		16 V <sub>DC</sub> AT + 40 °C;	10 V <sub>DC</sub> + 85 °C; 6.3 V <sub>DC</sub>	; AT + 125 °C		
10	W0 <sup>(1)</sup>	TL8W0106M016C	1.6	18	4.0	TBD
		20 V <sub>DC</sub> AT + 40 °C	; 13 V <sub>DC</sub> + 85 °C; 8 V <sub>DC</sub>	AT + 125 °C		
10	A0 <sup>(1)</sup>	TL8A0106M020C	4.0	15	5.0	0.105
33	В0	TL8B0336M020C	33	15	5.0	0.118
		25 V <sub>DC</sub> AT + 40 °C;	17 V <sub>DC</sub> + 85 °C; 10 V <sub>DC</sub>	AT + 125 °C		
4.7	W0 <sup>(1)</sup>	TL8W0475M025C	TBD	TBD	TBD	TBD
		35 V <sub>DC</sub> AT + 40 °C;	23 V <sub>DC</sub> + 85 °C; 14 V <sub>DC</sub>	AT + 125 °C		
3.3	A0 <sup>(1)</sup>	TL8A0335(1)035C	1.2	10	10.0	0.074

Notes

• Part number definition:

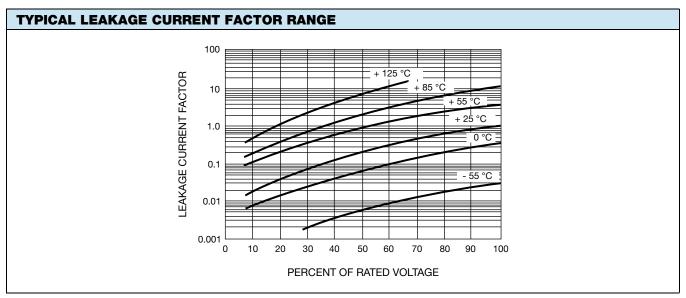
(1) Capacitance tolerance: K = 10 %, M = 20 %

<sup>(1)</sup> In development.



## **CAPACITORS PERFORMANCE CHARACTERISTICS**

ELECTRICAL PERFO	RMANCE CHAP	RACTERISTICS							
ITEM	PERFORMANCE	PERFORMANCE CHARACTERISTICS							
Category temperature range	- 55 °C to + 125 °C	C (with voltage deratin	g)						
Capacitance tolerance	± 20 %, ± 10 % (at	± 20 %, ± 10 % (at 120 Hz) 2 V <sub>RMS</sub> at + 25 °C using a capacitance bridge							
Dissipation factor (at 120 Hz)	Limits per Standar	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 120 Hz							
ESR (100 kHz)	Limits per Standar	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 100 kHz							
Leakage current		After application of RV applied to capacitors for 5 min using a steady source of power with 1 k $\Omega$ resistor in series with the capacitor under test, leakage current at 25 °C is not more than described in.							
	Rated voltage	- 55 °C/+ 40 °C	4 V	6.3 V	10 V	16 V	20 V	25 V	35 V
Operation temperatures	Category voltage	+ 40 °C/+ 85 °C	2.5 V	4.0 V	6.3 V	10 V	13 V	17 V	23 V
	Category voltage	+ 85 °C/+ 125 °C	1.6 V	2.5 V	4 V	6.3 V	8.0 V	10 V	14 V

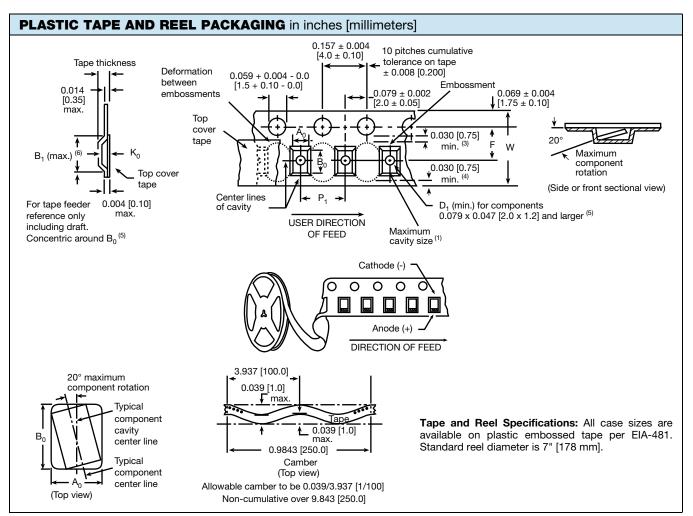


#### Notes

- At + 25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table
- At + 85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table
- At + 125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table

www.vishay.com

# Vishay Sprague



#### Notes

- · Metric dimensions will govern. Dimensions in inches are rounded and for reference only.
- (1) A<sub>0</sub>, B<sub>0</sub>, K<sub>0</sub>, are determined by the maximum dimensions to the ends of the terminals extending from the component body and/or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A<sub>0</sub>, B<sub>0</sub>, K<sub>0</sub>) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°.
- (2) Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum.
- <sup>(3)</sup> This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less.
- (4) This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less.
- <sup>(5)</sup> The embossed hole location shall be measured from the sprocket hole controlling the location of the embossement. Dimensions of embossement location shall be applied independent of each other.
- <sup>(6)</sup> B<sub>1</sub> dimension is a reference dimension tape feeder clearance only.

CARRIER TAPE DIMENSIONS in inches [millimeters]							
CASE CODE	TAPE SIZE	В <sub>1</sub> (МАХ.)	D <sub>1</sub> (MIN.)	F	K <sub>0</sub> (MAX.)	P <sub>1</sub>	w
A0	8 mm	0.165 [4.2]	0.039 [1.0]	0.138 ± 0.002 [3.5 ± 0.05]	0.094 [2.4]	0.157 ± 0.004 [4.0 ± 0.1]	0.315 ± 0.012 [8.0 ± 0.3]
W0	8 mm	0.094 [2.4]	0.029 [0.75]	0.138 ± 0.002 [3.5 ± 0.05]	0.045 [1.15]	0.157 ± 0.004 [4.0 ± 0.1]	0.315 ± 0.012 [8.0 ± 0.3]
W9	8 mm	0.126 [3.2]	0.029 [0.75]	0.138 ± 0.002 [3.5 ± 0.05]	0.045 [1.15]	0.157 ± 0.004 [4.0 ± 0.1]	0.315 ± 0.012 [8.0 ± 0.3]
B0	12 mm	0.181 [4.61]	0.059 [1.5]	0.217 ± 0.002 [5.5 ± 0.05]	0.049 [1.25]	$\begin{array}{c} 0.157 \pm 0.004 \\ [4.0 \pm 0.1] \end{array}$	0.472 ± 0.012 [12 ± 0.3]

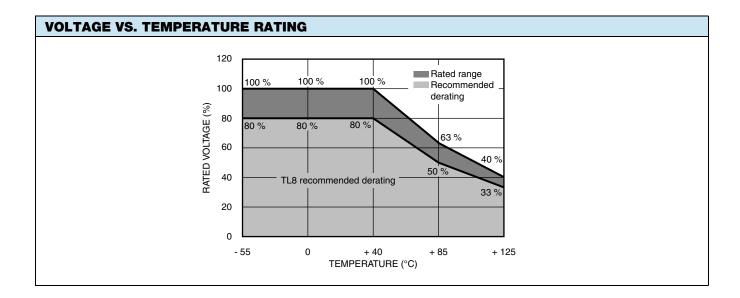
Revision: 15-Jan-13

Document Number: 40156

For technical questions, contact: <u>tantalum@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>



STANDARD PACKAGING QUANTITY				
CASE CODE	QUANTITY (pcs/reel)			
CASE CODE	7" REEL			
A0	2500			
W0, W9	3000			
B0	3000			



POWER DISSIPATION					
CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT + 25 °C (W) IN FREE AIR				
A0	0.055				
W0, W9	0.035				
B0	0.070				



TL8

Vishay Sprague

#### **RECOMMENDED REFLOW PROFILES** Capacitors should withstand Reflow profile as per J-STD-020 standard Tp ← T<sub>c</sub> = 5 °C Max. ramp-up rate = 3 °C/s Max. ramp-down rate = 6 °C/s TEMPERATURE (°C) T. T<sub>s max</sub> Preheat area ¥ ۲ T<sub>s min.</sub> 25 Time 25 °C to peak TIME (s) **PROFILE FEATURE** LEAD (Pb)-FREE ASSEMBLY Preheat/soak Temperature min. (T<sub>s min.</sub>) 150 °C 200 °C Temperature max. (T<sub>s max.</sub>) Time (t<sub>s</sub>) from (T<sub>s min.</sub> to T<sub>s max.</sub>) 60 s to 120 s Ramp-up 3 °C/s max. Ramp-up rate (T<sub>L</sub> to T<sub>p</sub>) 217 °C Liquidous temperature (TL) Time (t<sub>L</sub>) maintained above T<sub>L</sub> 60 s to 150 s Peak package body temperature (T<sub>p</sub>) max. 260 °C Time (tp) within 5 °C of the peak max. temperature 30 s Ramp-down Ramp-down rate (Tp to TL) 6 °C/s max. Time from 25 °C to peak temperature 8 min max.

PAD DIMENSIONS in inches [millimeters]					
	• •				
CASE CODE	A (MIN.)	B (NOM.)	C (NOM.)	D(NOM.)	
Wx-cases	0.059 [1.50]	0.031 [0.80]	0.039 [1.00]	0.102 [2.60]	
Ax-cases	0.071 [1.80]	0.067 [1.70]	0.053 [1.35]	0.187 [4.75]	
Bx-cases	0.118 [3.00]	0.071 [1.80]	0.065 [1.65]	0.207 [5.25]	

Revision: 15-Jan-13

7 For technical questions, contact: <u>tantalum@vishay.com</u>

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

www.vishay.com

### **GUIDE TO APPLICATION**

1. **AC Ripple Current:** The maximum allowable ripple current shall be determined from the formula:

$$I_{\rm RMS} = \sqrt{\frac{P}{R_{\rm ESR}}}$$

where,

- P = Power dissipation in W at + 25 °C as given in the tables in the product datasheets (Power Dissipation).
- $R_{\text{ESR}} = \begin{array}{l} \text{The capacitor equivalent series resistance at} \\ \text{the specified frequency} \end{array}$
- 2. **AC Ripple Voltage:** The maximum allowable ripple voltage shall be determined from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

or, from the formula:

$$V_{RMS} = Z_{\sqrt{\frac{P}{R_{ESR}}}}$$

where,

- P = Power dissipation in W at + 25 °C as given in the tables in the product datasheets (Power Dissipation).
- $\mathsf{R}_{\mathsf{ESR}} = \begin{array}{l} \mathsf{The \ capacitor \ equivalent \ series \ resistance \ at} \\ \mathsf{the \ specified \ frequency.} \end{array}$
- Z = The capacitor impedance at the specified frequency.
- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at + 25 °C.
- 3. **Reverse Voltage:** These capacitors are capable of withstanding peak voltages in the reverse direction equal to 10 % of the DC rating at + 25 °C, 5 % of the DC rating at + 85 °C and 1 % of the DC rating at + 125 °C.
- 4. Temperature Derating: If these capacitors are to be operated at temperatures above + 25 °C, the permissible RMS ripple current or voltage shall be calculated using the derating factors as shown:

TEMPERATURE	DERATING FACTOR
+ 25 °C	1.0
+ 85 °C	0.9
+ 125 °C	0.4

5. Power Dissipation: Power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I<sub>RMS</sub> value be established when calculating permissible operating levels. (Power dissipation calculated using + 25 °C temperature rise).

6. **Printed Circuit Board Materials:** Molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelanized steel).

#### 7. Attachment:

- 7.1 Solder Paste: The recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.
- 7.2 **Soldering:** Capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering, and hot plate methods. The soldering profile charts show recommended time/temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 2 °C per s. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.
- 7.2.1 **Backward and Forward Compatibility:** Capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.
- 8. **Cleaning (Flux Removal) After Soldering:** Molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC/ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.
- 8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. DO NOT EXCEED 9W/l at 40 kHz for 2 min.
- 9. Recommended Mounting Pad Geometries: Proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and/or circuit board design.

www.vishay.com/doc?40115
www.vishay.com/doc?40135
www.vishay.com/doc?49053
www.vishay.com/doc?40091
www.vishay.com/doc?40110

Revision: 15-Jan-13

For technical questions, contact: tantalum@vishay.com

Document Number: 40156

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

8



Vishay

# Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Vishay:

TL8A0227M004C TL8W9226M010C TL8A0107M010C TL8A0107M6R3C TL8B0336M020C